100% Material Declaration Data Sheet for 7 Series CSG324 Package

PK590 (v1.0) February 1, 2013

Average Weight: 0.6730 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.027377**	**4.068**
	Silicon	7440-21-3	100.00		0.027377	
Die Attach					**0.008562**	**1.272**
	Silver	7440-22-4	77.50		0.006636	
	Bismaleimide monomer	Trade Secret	15.00		0.001284	
	Acrylate monomer	Trade Secret	7.50		0.000642	
Mold Compound					**0.285271**	**42.388**
	Epoxy Resin	Trade secret	5.00		0.014264	
	Phenol Resin	Trade secret	3.00		0.008558	
	Phenol Novolac	9003-35-4	3.00		0.008558	
	Metal Hydroxide	Trade Secret	3.00		0.008558	
	Carbon black	1333-86-4	0.30		0.000856	
	Silica fused	60676-86-0	70.40		0.200830	
	Silica Dioxide	7631-86-9	15.00		0.042791	
	Silica, crystalline	14808-60-7	0.30		0.000856	
Copper Wire					**0.004921**	**0.731**
	Copper	7440-50-8	98.20		0.004832	
	Palladium	7440-05-3	1.80		0.000089	
Solder Ball					**0.114185**	**16.966**
	Tin	7440-31-5	96.50		0.110188	
	Silver	7440-22-4	3.00		0.003426	
	Copper	7440-50-8	0.50		0.000571	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					**0.232687**	**34.574**
	Copper	7440-50-8	15.70		0.036532	
	Nickel	7440-02-0	6.80		0.015823	
	Gold	7440-57-5	0.81		0.001885	
	Glass fiber	65997-17-3	20.14		0.046863	
	Non halogen fire retardant	NA	0.01		0.000023	
	BT core	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	46.11		0.107292	
	Solder mask	147-14-8 7727-43-7 7631-86-9 14807-96-6 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7	10.43		0.024269	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/01/2013	1.0	Xilinx Initial Release

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